

# 4V Drive Pch MOSFET

## RSD160P05

### ● Structure

Silicon P-channel MOSFET

### ● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.

### ● Application

Switching

### ● Packaging specifications

Type	Package	Taping
	Code	TL
	Basic ordering unit (pieces)	2500
RSD160P05		○

### ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter	Symbol	Limits	Unit	
Drain-source voltage	V <sub>DSS</sub>	-45	V	
Gate-source voltage	V <sub>GSS</sub>	±20	V	
Drain current	Continuous	I <sub>D</sub>	±16	A
	Pulsed	I <sub>DP</sub> *1	±32	A
Source current (Body Diode)	Continuous	I <sub>S</sub>	-16	A
	Pulsed	I <sub>SP</sub> *1	-32	A
Power dissipation	P <sub>D</sub> *2	20	W	
Channel temperature	T <sub>ch</sub>	150	°C	
Range of storage temperature	T <sub>stg</sub>	-55 to +150	°C	

\*1 Pw≤10μs, Duty cycle≤1%

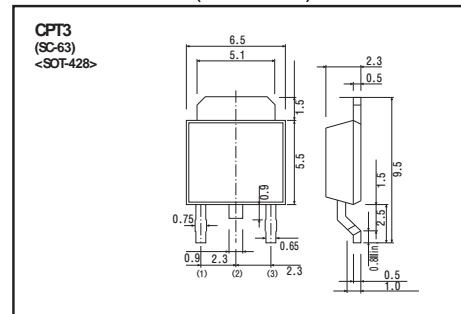
\*2 T<sub>c</sub>=25°C

### ● Thermal resistance

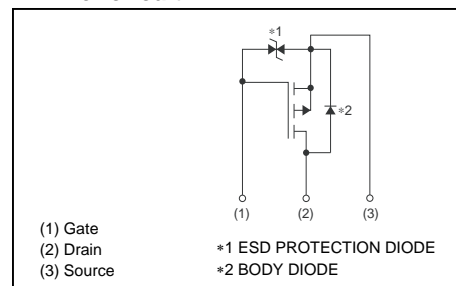
Parameter	Symbol	Limits	Unit
Channel to Case	R <sub>th(ch-c)</sub> *	6.25	°C / W

\* T<sub>c</sub>=25°C

### ● Dimensions (Unit : mm)



### ● Inner circuit



(1) Gate  
(2) Drain  
(3) Source

\*1 ESD PROTECTION DIODE  
\*2 BODY DIODE

●Electrical characteristics ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	-	-	$\pm 10$	$\mu\text{A}$	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$
Drain-source breakdown voltage	$V_{(BR)DSS}$	-45	-	-	V	$I_D=-1\text{mA}$ , $V_{GS}=0\text{V}$
Zero gate voltage drain current	$I_{DSS}$	-	-	-1	$\mu\text{A}$	$V_{DS}=-45\text{V}$ , $V_{GS}=0\text{V}$
Gate threshold voltage	$V_{GS(th)}$	-1.0	-	-3.0	V	$V_{DS}=-10\text{V}$ , $I_D=-1\text{mA}$
Static drain-source on-state resistance	$R_{DS(on)}^*$	-	35	50	m $\Omega$	$I_D=-16\text{A}$ , $V_{GS}=-10\text{V}$
		-	45	63		$I_D=-8\text{A}$ , $V_{GS}=-4.5\text{V}$
		-	50	70		$I_D=-8\text{A}$ , $V_{GS}=-4.0\text{V}$
Forward transfer admittance	$ Y_{fs} ^*$	8.0	-	-	S	$I_D=-8\text{A}$ , $V_{DS}=-10\text{V}$
Input capacitance	$C_{iss}$	-	2000	-	pF	$V_{DS}=-10\text{V}$
Output capacitance	$C_{oss}$	-	250	-	pF	$V_{GS}=0\text{V}$
Reverse transfer capacitance	$C_{rss}$	-	140	-	pF	$f=1\text{MHz}$
Turn-on delay time	$t_{d(on)}^*$	-	13	-	ns	$I_D=-8.0\text{A}$ , $V_{DD}=-25\text{V}$
Rise time	$t_r^*$	-	22	-	ns	$V_{GS}=-10\text{V}$
Turn-off delay time	$t_{d(off)}^*$	-	90	-	ns	$R_L=3.1\Omega$
Fall time	$t_f^*$	-	50	-	ns	$R_G=10\Omega$
Total gate charge	$Q_g^*$	-	16.0	-	nC	$V_{DD}=-25\text{V}$
Gate-source charge	$Q_{gs}^*$	-	5.2	-	nC	$I_D=-16\text{A}$ ,
Gate-drain charge	$Q_{gd}^*$	-	5.0	-	nC	$V_{GS}=-5\text{V}$

\*Pulsed

●Body diode characteristics (Source-Drain) ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward Voltage	$V_{SD}^*$	-	-	-1.2	V	$I_s=-16\text{A}$ , $V_{GS}=0\text{V}$

\*Pulsed

●Electrical characteristic curves (Ta=25°C)

Fig.1 Typical Output Characteristics ( I )

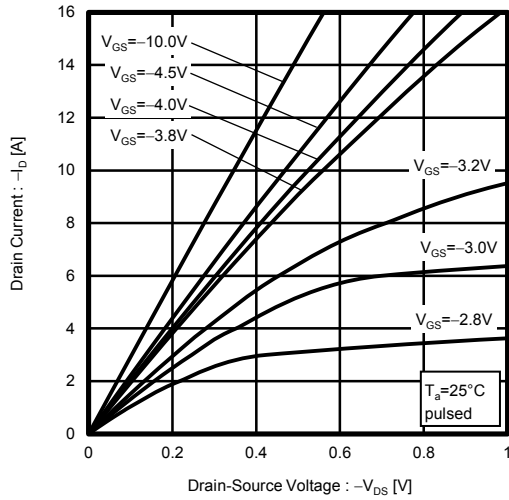


Fig.2 Typical Output Characteristics ( II )

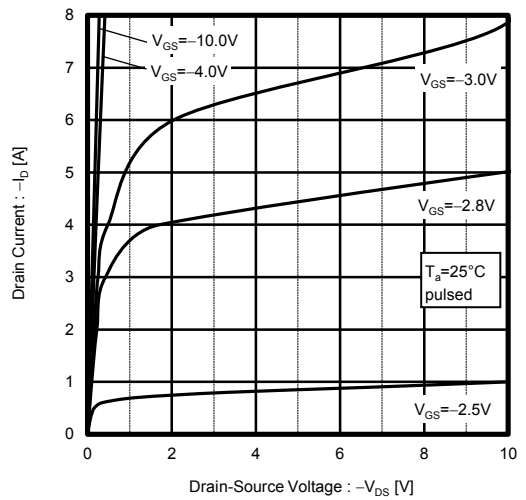


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

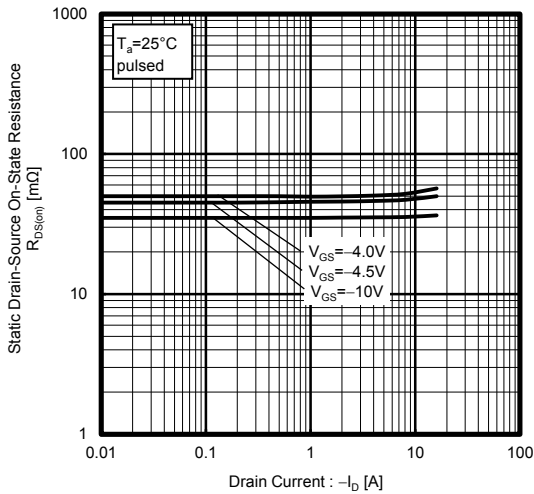


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

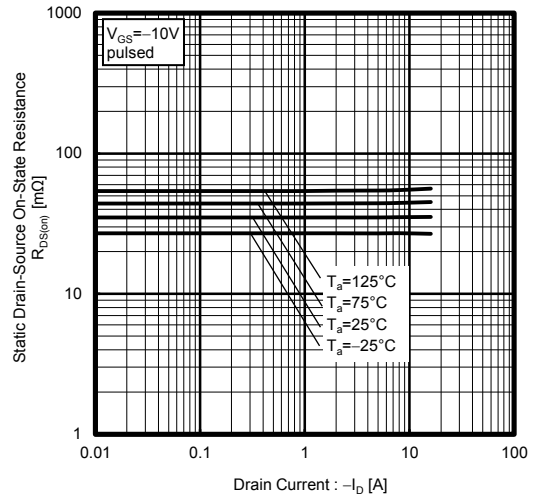


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

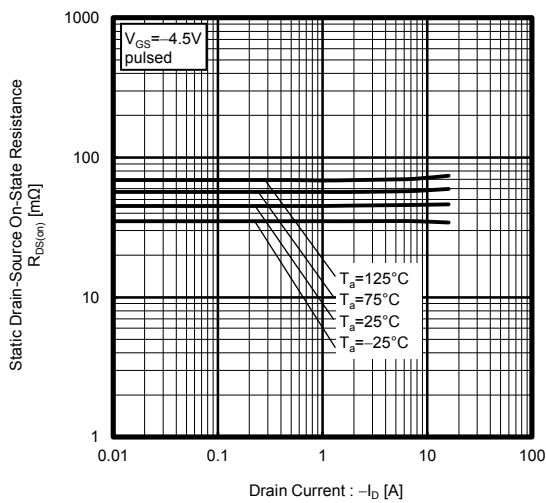


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current

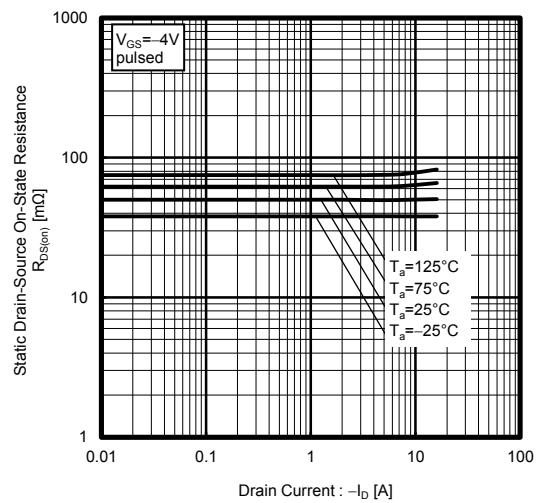


Fig.7 Forward Transfer Admittance vs. Drain Current

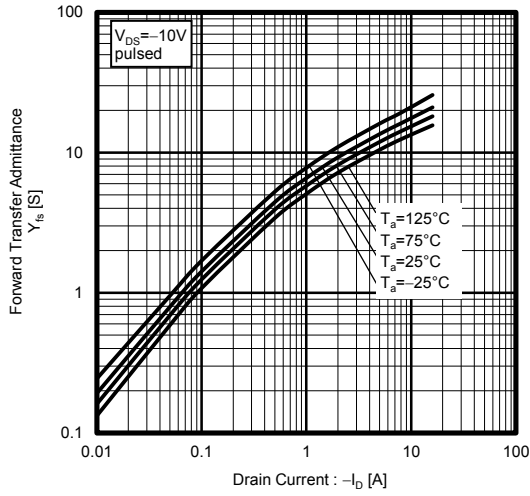


Fig.8 Typical Transfer Characteristics

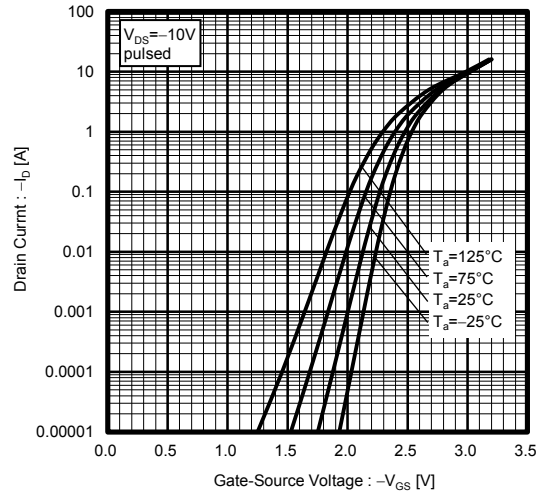


Fig.9 Source Current vs. Source-Drain Voltage

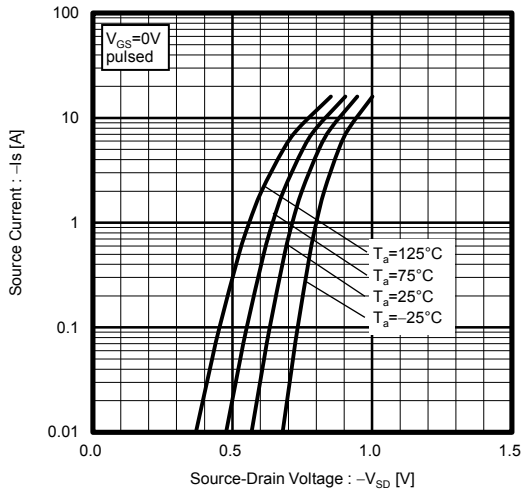


Fig.10 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

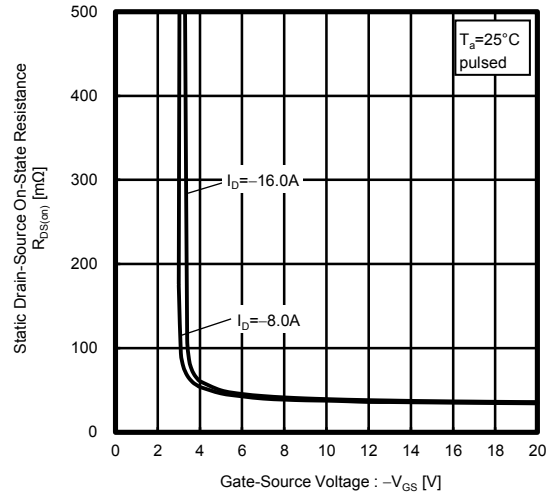


Fig.11 Switching Characteristics

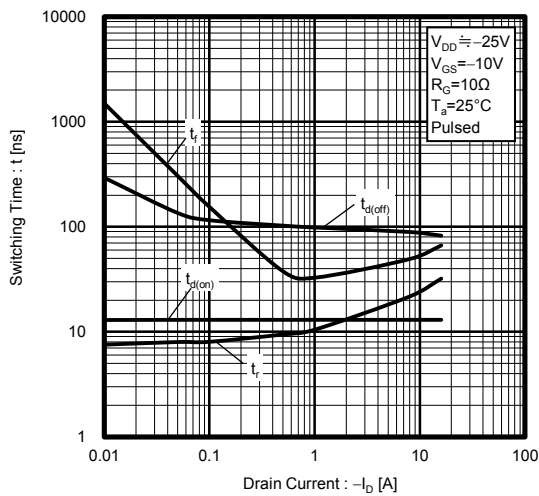


Fig.12 Dynamic Input Characteristics

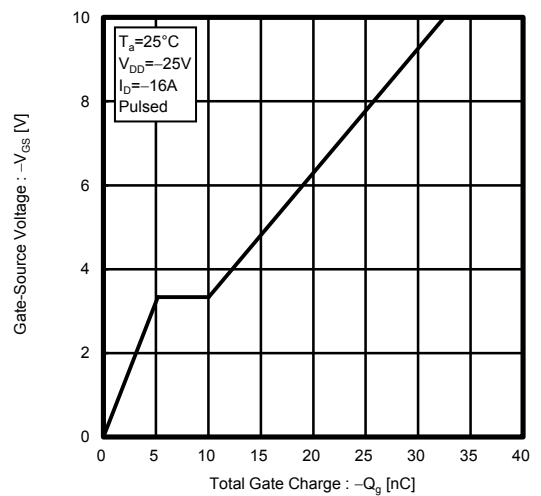


Fig.13 Typical Capacitance vs. Drain-Source Voltage

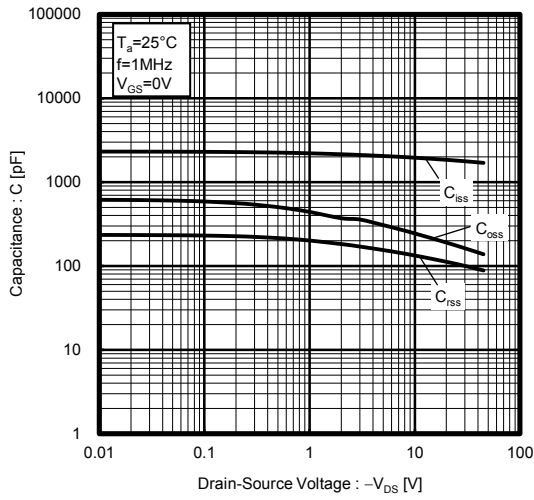


Fig.14 Maximum Safe Operating Area

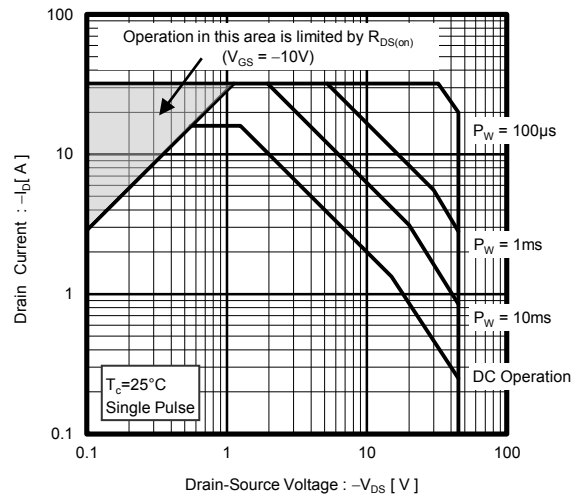
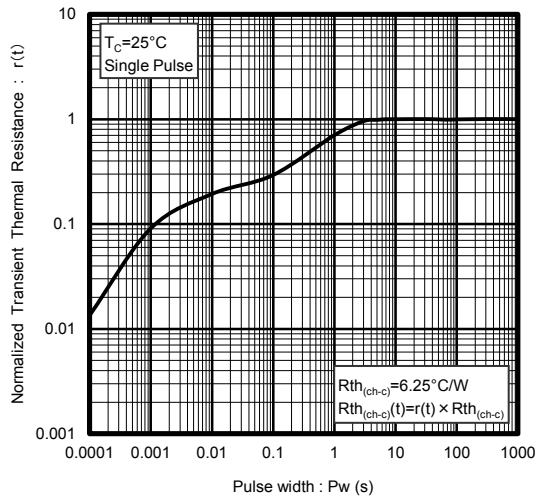


Fig.15 Normalized Transient Thermal Resistance v.s. Pulse Width



● Measurement circuits

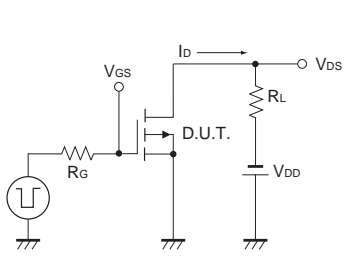


Fig.1-1 Switching Time Measurement Circuit

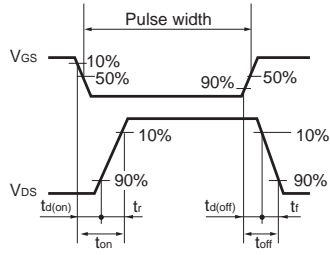


Fig.1-2 Switching Waveforms

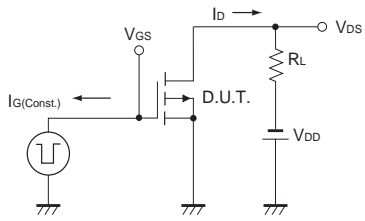


Fig.2-1 Gate Charge Measurement Circuit

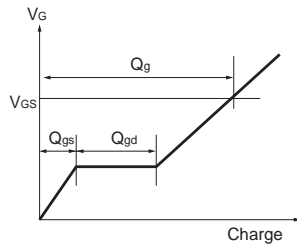


Fig.2-2 Gate Charge Waveform

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